

Serial No. 10/681,983
October 24, 2005
Reply to the Office Action dated July 27, 2005
Page 2 of 6

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-10 (canceled).

Claim 11 (currently amended): An integrated circuit package comprising:
a first leadframe;
a second leadframe laminated to a portion of a side of said first leadframe
thereby providing a multi-layer laminated leadframe;
a semiconductor die mounted to another portion of said side of said first
leadframe; and
a plurality of contact balls mounted on said semiconductor die.

Claim 12 (previously presented): An integrated circuit package comprising:
a first leadframe;
a second leadframe laminated to a portion of said first leadframe thereby
providing a multi-layer laminated leadframe;
a semiconductor die having opposing first and second surfaces, the first surface
of said semiconductor die being mounted to another portion of said first leadframe; and
a third leadframe laminated to at least a portion of said second surface of said
semiconductor die.

Claim 13 (previously presented): The integrated circuit package according to
claim 11, wherein said first leadframe comprises a copper strip having silver plating on
one surface and said second leadframe is soldered to an opposing second surface
thereof.

Serial No. 10/681,983
October 24, 2005
Reply to the Office Action dated July 27, 2005
Page 3 of 6

Claim 14 (previously presented): The integrated circuit package according to claim 11, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

Claim 15 (Original): The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

Claim 16 (previously presented): The integrated circuit package according to claim 11 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.